



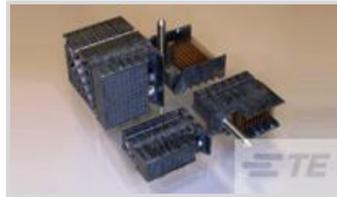
**IMPACT**

TE Part # 2007850-3

TE Internal #: 2007850-3

[View on TE.com >](#)

Connectors > PCB Connectors > Backplane Connectors > High Speed Connectors



Connector System: **Board-to-Board**

Number of Positions: **150**

Row-to-Row Spacing: **1.35 mm [ .053 in ]**

Mating Alignment: **With**

Mating Alignment Type: **Polarization**

**Features**

**Product Type Features**

Make First / Break Last	No
Product Type	Connector
Signal Arrangement	Differential
Connector Type	Header
Connector System	Board-to-Board
Row-to-Row Spacing	1.35 mm[.053 in]
Connector Style	Plug
Shrouded	Fully Shrouded
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board

**Configuration Features**

Number of Ground Positions	50
Number of Pairs	50
Stackable	No
Number of Signal Positions	100
Number of Positions	150
Number of Rows	15
Number of Columns	10
Board-to-Board Configuration	Right Angle, Vertical
PCB Mount Orientation	Vertical

Guide Location	Unguided
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### Electrical Characteristics

Operating Voltage	30 VDC
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Impedance	100 $\Omega$
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### Signal Characteristics

Number of Differential Pairs per Column	5
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Data Rate	20 – 25 Gb/s
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### Contact Features

Contact Type	Pin
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Underplate Material Thickness	1.27 $\mu\text{m}$ [50 $\mu\text{in}$ ]
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Contact Transmits (Typical)	Signal (Data)
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Contact Layout	Inline
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PCB Contact Termination Area Plating Material Thickness	.76 – 1.52 $\mu\text{m}$ [30 – 60 $\mu\text{in}$ ]
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Contact Mating Area Plating Material	Gold
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Contact Design	Dual Beam
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Contact Termination Area Plating Material	Tin
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Contact Mating Area Plating Thickness	.76 $\mu\text{m}$ [29.92 $\mu\text{in}$ ]
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PCB Contact Termination Area Plating Material Finish	Matte
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Contact Length	5.5 mm[.217 in]
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Contact Underplating Material	Nickel
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Contact Base Material	Copper Alloy
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Contact Current Rating (Max)	.75 A
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### Termination Features

Termination Method to Printed Circuit Board	Through Hole - Press-Fit
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### Mechanical Attachment

Mating Retention	Without
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Guide Hardware	Without
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PCB Mount Retention	With
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PCB Mount Retention Type	Action/Compliant Tail
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Mating Alignment	With
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Mating Alignment Type	Polarization
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Connector Mounting Type	Board Mount
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### Housing Features

Housing Material	LCP - GF (Liquid Crystal Polymer)
Housing Color	Black
End Wall Location	Dual
Centerline (Pitch)	1.9 mm[.075 in]

### Dimensions

Height	11.95 mm[.47 in]
PCB Thickness (Recommended)	1 mm
Stack Height	11.95 mm
Width	24.8 mm[.976 in]
Tail Length	1.4 mm[.055 in]
Length	21.7 mm[.854 in]
PCB Hole Diameter	.46 mm[.018 in]

### Usage Conditions

Operating Temperature Range	-55 – 85 °C[-67 – 185 °F]
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### Operation/Application

For Use With	Receptacle Assembly
Circuit Application	Signal

### Industry Standards

UL Flammability Rating	UL 94V-0
UL File Number	E28476
UL Rating	Recognized
CSA Certified	Yes

### Packaging Features

Packaging Method	Box & Tube, Package
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### Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2019 (197)

Candidate List Declared Against: JUN 2012  
(84)

Halogen Content

Not Yet Reviewed for halogen content

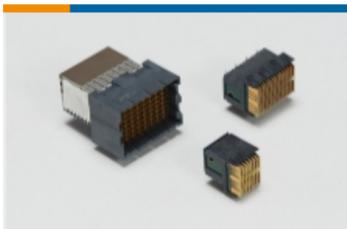
Solder Process Capability

Not applicable for solder process capability

Product Compliance Disclaimer

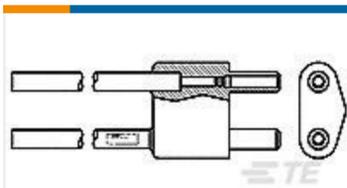
This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulations, TE's information on SVHC in articles for this part number is still based on the European Chemical Agency (ECHA) 'Guidance on requirements for substances in articles' (Version: 2, April 2011), applying the 0.1% weight on weight concentration threshold at the finished product level. TE is aware of the European Court of Justice ruling of September 10th, 2015 also known as O5A (Once An Article Always An Article) stating that, in case of 'complex object', the threshold for a SVHC must be applied to both the product as a whole and simultaneously to each of the articles forming part of its composition. TE has evaluated this ruling based on the new ECHA "Guidance on requirements for substances in articles" (June 2017, version 4.0) and will be updating its statements accordingly.

Also in the Series | **IMPACT**



High Speed Backplane Connectors(1824)

Customers Also Bought



TE Part #866559-1  
2 PIN MICR-MINI PLUG



TE Part #2-1617352-0  
SMGAD-12=SMGAD .100  
GRID SMD D



TE Part #1-530745-9  
MINI BX RECPT ASSY, 90P  
SEALED



TE Part #1617124-1  
JMAPD-12XP = M39016  
/15-037P



TE Part #2007884-2  
IMP100S,H,V6P10C,UG,  
OEW39,4.9



TE Part #3-1617542-2  
JMAPD-12XM=M39016/15-  
037M



TE Part #3-2040714-6  
.5FHR04H,220,S,GIG,30/Sn,  
TR,NSYes



TE Part #  
ZPF000000000015471  
DMC-MD 80 M 01

## Documents

### CAD Files

#### Customer View Model

[ENG\\_CVM\\_CVM\\_2007850-3\\_A.2d\\_dxf.zip](#)

English

#### 3D PDF

3D

#### Customer View Model

[ENG\\_CVM\\_CVM\\_2007850-3\\_A.3d\\_igs.zip](#)

English

#### Customer View Model

[ENG\\_CVM\\_CVM\\_2007850-3\\_A.3d\\_stp.zip](#)

English

### Product Specifications

#### Application Specification

English